

INTRODUCTION

Fast and easy breadboarding of circuits using the PA241DF is possible with the EK13 evaluation kit. The amplifier may be surface mounted directly to the PC board. The PA241DF is soldered to a 2-square inch area of foil on the PC board for heat sinking. This foil heat sink is connected to -Vs. Connections are provided for required power supply bypassing, phase compensation components, and a current limit resistor. A large area for component mounting provides flexibility and makes a multitude of circuit configurations possible.

PARTS LIST

Part #	Description	Quantity
EVAL15	PC Board	1
OX7R105KWN	1 μ F Ceramic Capacitor	1
HS24	Heatsink	1

ASSEMBLY

The PA241DF is a surface mount device and should be assembled to the EVAL15 PC board using surface mount processes. Solder paste may be dispensed or screen-printed on the DUT pads. The heat tab on the back of the PA241DF provides maximum heat dissipation capabilities when soldered to the PCB metalization that runs under the DUT on the DUT side of the board. Solder should be applied here also. For prototype purposes, the tab can be thermally connected to the PCB metalization using thermal grease.

The PA241DF and HS24 should be reflowed to the PCB using a solder reflow furnace. If this is not available, a heat plate capable of solder reflow temperatures may be used. or, though time consuming, the leads may be soldered individually to the PCB with a soldering iron. In this case the use of thermal grease under the heat tab is recommended instead of solder for the thermal connection.

CAUTION

High voltages will be present. Use caution in handling and probing when power is applied.



